

INDIVIDUAL SPECIFICATION SHEET

Product Name: Current Sensing Resistors

Part Number:SMB Series

Revision: A



Dongguan TLC Electronic Technology Co., LTD

No.18,5th GaoLi Road,TangXia Town,DongGuan,GuangDong,P.R China 523710

TEL: 86-0769-3892 0511

FAX: 86-0769-8793 2077

Http: www.tlcet.com.cn

Rev.	Effective Date	Changed Contents
A	2021-6-25	New release

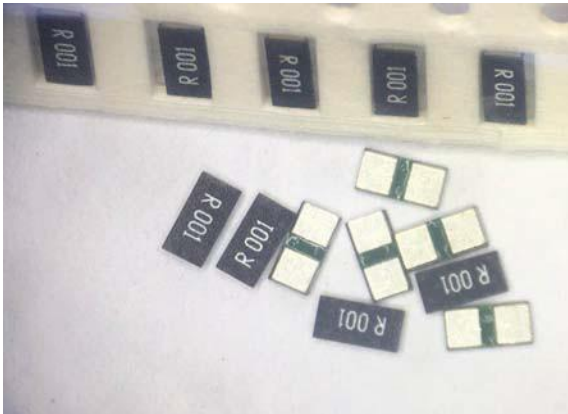
☞ The individual specification sheet are the property of Dongguan TLC electronic technology Co.,Ltd and shall not be copied or used as commercial purposes without permission.

PREPEARED BY



APPROVED BY





General

- Chip size from 0402 to 1206
- Resistance value from 1mΩ to 25mΩ
- Low thermal EMF
- Low TCR
- Lead free, RoHS compliant for global
- Applications and halogen free

Application

- Switching model power supply.
- Battery pack.
- Notebook, personal computer.
- Test Instrument.
- Power Amplifier.

Electrical Specifications

Type	Power Rating at 70°C(W)	Resistance Range (mΩ)	TCR (ppm/°C)	Resistance tolerance	Operation Temp. Range
0402	0.3	2.5<R≤3	±150	±1%(F),±1.5%(E),±2%(G)	-55°C~155°C
		5<R≤25	±100		
0603	0.3	2≤R≤5	±100	±1%(F)	
		6≤R≤20	±75		
0805	0.5	2≤R≤5	±75		
		6≤R≤20	±50		
1206	1.0	1	±75	±1%(F),±1.5%(E)	
		2≤R≤4	±75	±1%(F)	
		5≤R≤20	±50	±1%(F)	

Part Number information

SMB 12 A 1 F R002 I
【1】 **【2】** **【3】** **【4】** **【5】** **【6】** **【7】**

【1】 Series Name: SART Metal Foil PCB Type

【2】 Chip size: 12:1206 08:0805 06:0603 04:0402

【3】 Material Code:A:Alloy

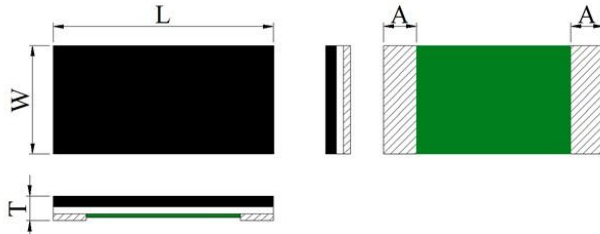
【4】 Power Code:1:1W A:0.5W M:0.3W

【5】 Resistance Tolerance: F:±1% E: ±1.5% G: ±2%

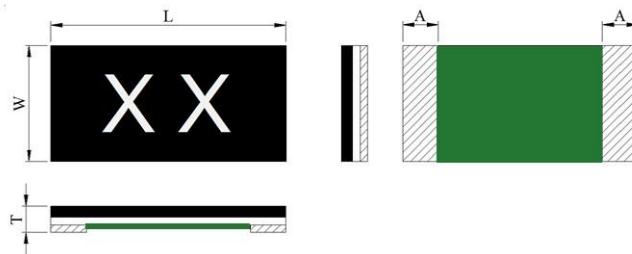
【6】 Resistance Code: R002=2mΩ

【7】 Packaging Code: T:Tape& Reel B: Bulk Pack

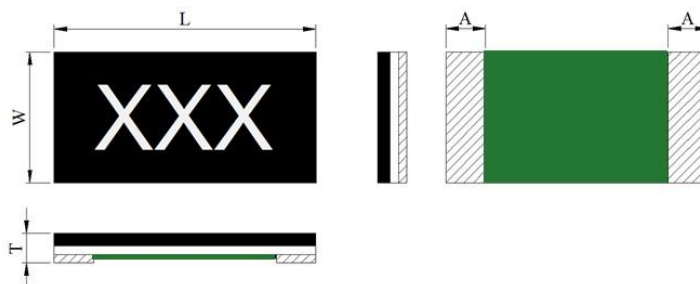
Dimensions



Type	Resistance Range (mΩ)	W (mm)	L (mm)	T (mm)	A (mm)
0402	2.5<R≤3	0.55±0.10	1.00±0.10	0.30±0.05	0.30±0.10
	5<R≤25	0.55±0.10	1.00±0.10	0.30±0.05	0.23±0.10

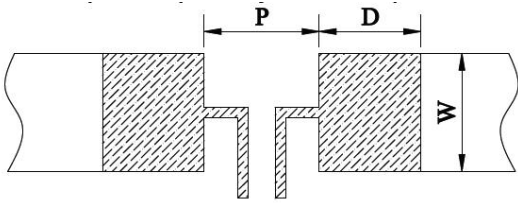


Type	Resistance Range (mΩ)	W (mm)	L (mm)	T (mm)	A (mm)
0603	2	0.80±0.25	1.60±0.25	0.40±0.25	0.45±0.20
	2.5<R≤3	0.80±0.25	1.60±0.25	0.40±0.25	0.35±0.20
	4≤R≤20	0.80±0.25	1.60±0.25	0.40±0.25	0.30±0.20



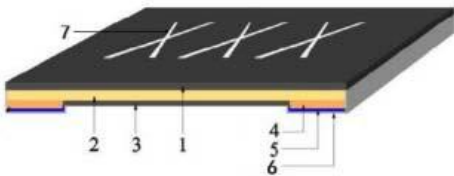
Type	Resistance Range (mΩ)	W (mm)	L (mm)	T (mm)	A (mm)
0805	2	1.25±0.25	2.00±0.25	0.40±0.25	0.60±0.20
	3≤R≤20	1.25±0.25	2.00±0.25	0.40±0.25	0.40±0.20
1206	1	1.60±0.25	3.20±0.25	0.40±0.25	1.25±0.30
	2	1.60±0.25	3.20±0.25	0.40±0.25	1.05±0.30
	3	1.60±0.25	3.20±0.25	0.40±0.25	0.80±0.30
	4≤R≤20	1.60±0.25	3.20±0.25	0.40±0.25	0.60±0.30

Recommended Land Patterns



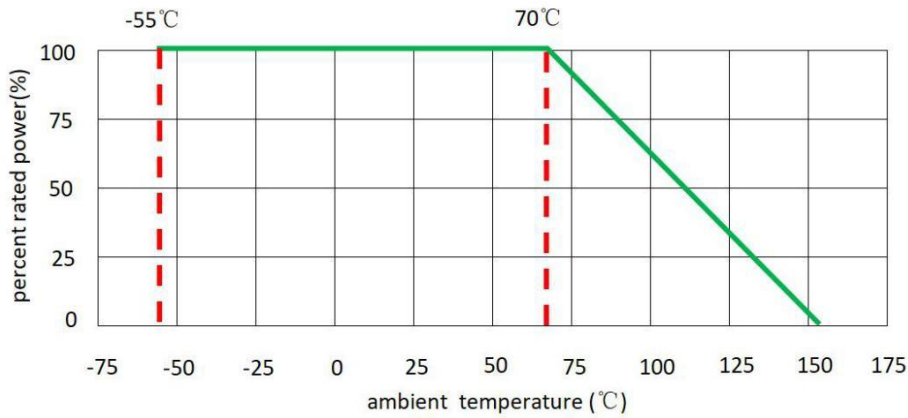
Type	Resistance range (mΩ)	P (mm)	W (mm)	D (mm)
0402	2.5<R≤3	0.35	0.60	0.60
	5<R≤25	0.40	0.60	0.60
0603	2	0.38	0.92	1.41
	2.5≤R≤3	0.50	0.92	1.35
	4≤R≤20	0.60	0.92	1.30
0805	2	0.50	1.44	1.55
	3≤R≤20	0.80	1.44	1.40
1206	1	0.50	1.84	2.15
	2	0.60	1.84	2.10
	3≤R≤20	1.20	1.84	1.80

Materials



No.	Materials	No.	Materials
1	Epoxy substrate	5	Nickel
2	Alloy	6	Tin
3	Protective coating	7	Marking
4	Copper	/	/

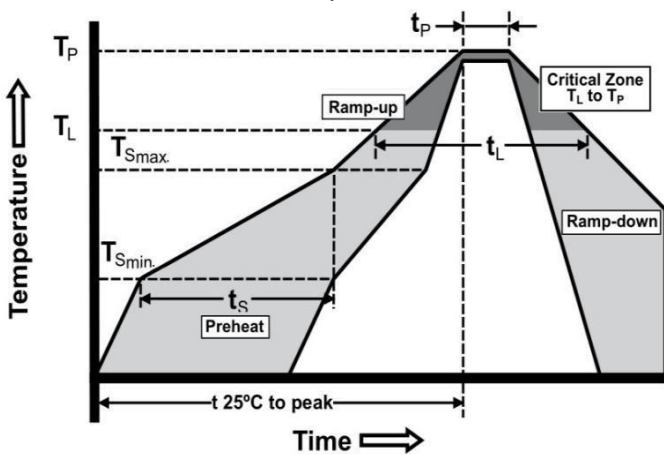
Power Derating Curve



Recommended Solder Curve

1. Infrared Reflow

- Temperature: 260°C.
- Time: 10 sec Max.
- Recommend Reflow profile



Profile Feature	Pb-Free Assembly
Average Ramp-up Rate (T _{Smax} to T _p)	3°C/sec Max.
Preheat Temperature Min.(T _{Smin}) Temperature Max.(T _{Smax}) Time(T _{Smin} to T _{Smax})	150°C 200°C 60sec~120sec
Peak Temperature(T _p)	260°C
Time within 5°C of actual Peak Temperature(T _p)	5sec
Melting tin time(T _L)	20sec~30sec
Ramp-down Rate	6°C/sec Max.
Time 25°C to peak Temperature	8 min Max.

2. Hand Soldering

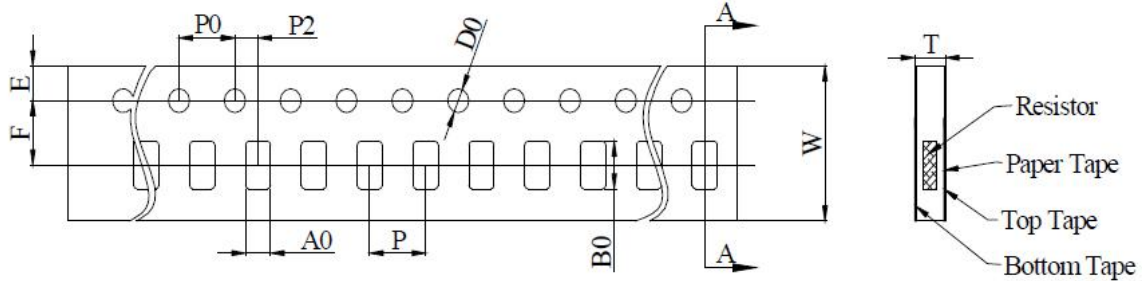
- Temperature: 350°C
- Time: 5sec Max.

Product Characteristics

Item	Test condition / Methods	Performance	Standard
Short Time Overload	0805 $2m\Omega \leq R \leq 10m\Omega$: $P = 5*Pr$; 1206 $1m\Omega \leq R \leq 10m\Omega$: $P = 5*Pr$; $T = 25^\circ C \pm 2^\circ C$, $t = 5sec$ Rest specifications: $P = 2.5*Pr$; $T = 25 \pm 2^\circ C$, $t = 5sec$	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.13
Temperature Coefficient of Resistance (TCR)	$TCR = (R - R_0) / R_0 (T_2 - T_1) \times 10^6$ Test temperature: $+25^\circ C \sim +125^\circ C$	Refer to SART Spec	IEC 60115-1 4.8
Thermal Shock	$-55^\circ C$ (30min) / $+155^\circ C$ (30min) , 100 cycles	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.19
Resistance to Solder Heat	$270^\circ C \pm 5^\circ C$, 20sec \pm 1sec	$ \Delta R \leq \pm(1\% + 0.5m\Omega)$	IEC 60115-1 4.18
Solderability	$245^\circ C \pm 5^\circ C$, 3sec \pm 0.5sec	95% coverage Min.	IEC 60115-1 4.17
Load Life	1000 hours at rated power, $70^\circ C \pm 2^\circ C$, 1.5hours "ON", 0.5hours "OFF"	$ \Delta R \leq \pm(2\% + 0.5 m\Omega)$	IEC 60115-1 4.25
Moisture Load Life ($60^\circ C$ 、95%RH)	$T = 60^\circ C \pm 2^\circ C$; RH=95% ; $V_{test} = V_{max}$; $t = 1.5hours$ "ON" , 0.5hours "OFF", 1000hours	$ \Delta R \leq \pm(2\% + 0.5 m\Omega)$	IEC 60115-1 4.24
Bending test	Bending width 2mm, Epoxy thickness 1.6mm, Fulcrums distance 90mm	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC 60115-1 4.33
High Temp. Exposure	$155^\circ C \pm 2^\circ C$, 1000hours	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.25
Low Temp. Storage	$-55^\circ C \pm 2^\circ C$, 1000hours	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.25
Mechanical Shock	$a = 100G$, $t = 11ms$, 5 times shock	$ \Delta R \leq \pm(1\% + 0.5 m\Omega)$	IEC60115-1 4.21

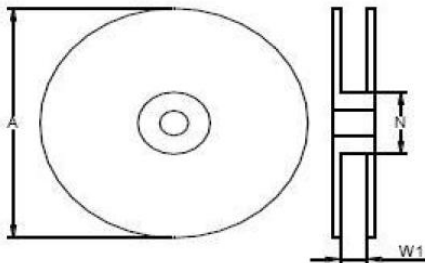
Packaging

1. Embossed Tape Dimensions



Type	A0 (mm)	B0 (mm)	W (mm)	F (mm)	E (mm)
0402	0.65±0.10	1.10±0.10	8.00±0.30	3.50±0.10	1.75±0.10
0603	0.98±0.10	1.85±0.10	8.00±0.30	3.50±0.10	1.75±0.10
0805	1.55±0.10	2.30±0.10	8.00±0.30	3.50±0.10	1.75±0.10
1206	2.05±0.20	3.65±0.20	8.00±0.30	3.50±0.10	1.75±0.10
Type	P (mm)	P2 (mm)	P0 (mm)	D0 (mm)	T (mm)
0402	2.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.42±0.05
0603	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.60±0.05
0805	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.75±0.10
1206	4.00±0.10	2.00±0.10	4.00±0.10	1.50±0.10	0.75±0.10

2.Reel Dimensions

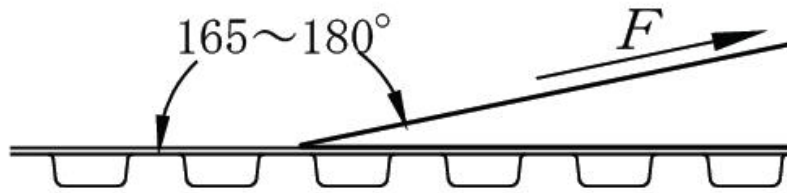


Type	A (mm)	N (mm)	W1 (mm)
0402	178.00±5.00	60.00±2.00	9.00±1.00
0603			
0805			
1206			

3..Quantity of Package

Type	0402	0603	0805	1206
Quantity(pcs)	10000		5000	

4. Peeling Test



F=Peeling Strength:0.1-1.0N(10~100gf)

Storage

- The ambient temperature shall be between 5°C~30°C.
- The relative humidity recommended for storage is between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.